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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Preferred Devices

Power Management, Dual Transistors

NPN Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- These are Pb-Free Devices

Rating

MAXIMUM RATINGS

	- ,	1 0.110.0				
$\mathbf{Q_1}$ (T _A = 25°C unless otherwise noted, common for Q ₁ and Q ₂)						
Collector-Base Voltage	V _{CBO}	50	Vdc			
Collector-Emitter Voltage	V _{CEO}	50	Vdc			
Collector Current	I _C	100	mAdc			
Electrostatic Discharge	ESD	HBM Class 1 MM Class B				

Symbol

Value

Unit

$Q_2 (T_A = 25^{\circ}C)$

Collector-Emitter Voltage	V_{CEO}	-12	Vdc	
Collector-Base Voltage	V _{CBO}	-15	Vdc	
Emitter-Base Voltage	V _{EBO}	-6.0	Vdc	
Collector Current - Peak - Continuous	I _C	-1.0 (Note 1) -0.5	Adc	
Electrostatic Discharge	ESD	HBM Class 3B MM Class C		

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit		
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	P _D	357 (Note 2) 2.9 (Note 2)	mW mW/°C		
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350 (Note 2)	°C/W		
Characteristic (Both Junctions Heated)	Symbol	Max	Unit		
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	P _D	500 (Note 2) 4.0 (Note 2)	mW mW/°C		
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	250 (Note 2)	°C/W		
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C		

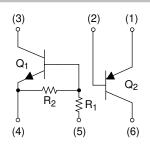
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. Single pulse 1.0 ms.
- 2. FR-4 @ Minimum Pad.



ON Semiconductor®

http://onsemi.com





SOT-563 CASE 463A PLASTIC

MARKING DIAGRAM



UY = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
EMF5XV6T5	SOT-563 (Pb-Free)	8000/Tape & Reel
EMF5XV6T5G	SOT-563 (Pb-Free)	8000/Tape & Reel

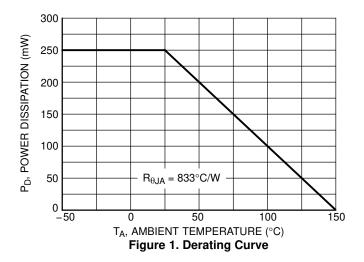
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted, common for Q_1 and Q_2)

Characteristic			Min	Тур	Max	Unit
Q ₁ OFF CHARACTERISTICS						
Collector-Base Cutoff Current	I _{CBO}	ı	-	100	nAdc	
Collector-Emitter Cutoff Current	$(V_{CE} = 50 \text{ V}, I_{B} = 0)$	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current	$(V_{EB} = 6.0 \text{ V}, I_{C} = 0)$	I _{EBO}	-	-	0.1	mAdc
Collector-Base Breakdown Voltage	$(I_C = 10 \ \mu A, \ I_E = 0)$	V _{(BR)CBO}	50	_	_	Vdc
Collector-Emitter Breakdown Voltage (N	lote 3) $(I_C = 2.0 \text{ mA}, I_B = 0)$	$V_{(BR)CEO}$	50	-	-	Vdc
ON CHARACTERISTICS (Note 3)						
DC Current Gain	$(V_{CE} = 10 \text{ V}, I_{C} = 5.0 \text{ mA})$	h _{FE}	80	140	_	
Collector-Emitter Saturation Voltage	$(I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA})$	V _{CE(sat)}	-	_	0.25	Vdc
Output Voltage (on)	$(V_{CC} = 5.0 \text{ V}, V_B = 3.5 \text{ V}, R_L = 1.0 \text{ k}\Omega)$	V _{OL}	-	-	0.2	Vdc
Output Voltage (off)	$(V_{CC} = 5.0 \text{ V}, V_B = 0.5 \text{ V}, R_L = 1.0 \text{ k}\Omega)$	V _{OH}	4.9	_	-	Vdc
Input Resistor		R1	32.9	47	61.1	kΩ
Resistor Ratio		R1/R2	0.8	1.0	1.2	
Q ₂ OFF CHARACTERISTICS						
Collector - Emitter Breakdown Voltage	$(I_C = -10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-12	-	_	Vdc
Collector - Base Breakdown Voltage	$(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	-15	-	-	Vdc
Emitter – Base Breakdown Voltage	$(I_E = -0.1 \text{ mAdc}, I_C = 0)$	$V_{(BR)EBO}$	-6.0	-	-	Vdc
Collector Cutoff Current	$(V_{CB} = -15 \text{ Vdc}, I_{E} = 0)$	I _{CBO}	-	-	-0.1	μAdc
Emitter Cutoff Current	$(V_{EB} = -6.0 \text{ Vdc})$	I _{EBO}	-	-	-0.1	μAdc
ON CHARACTERISTICS						
DC Current Gain (Note 4)	$(I_C = -10 \text{ mA}, V_{CE} = -2.0 \text{ V})$	h _{FE}	270	-	680	
Collector - Emitter Saturation Voltage (N	lote 4) $(I_C = -200 \text{ mA}, I_B = -10 \text{ mA})$	V _{CE(sat)}	-	-	-250	mV
Base - Emitter Saturation Voltage (Note	4) $(I_C = -150 \text{ mA}, I_B = -20 \text{ mA})$	V _{BE(sat)}	-	-0.81	-0.90	V
Base - Emitter Turn-on Voltage (Note 4	$(I_C = -150 \text{ mA}, V_{CE} = -3.0 \text{ V})$	V _{BE(on)}	-	-0.81	-0.875	V
Input Capacitance	$(V_{EB} = 0 \text{ V, f} = 1.0 \text{ MHz})$	C _{ibo}	-	52	-	pF
Output Capacitance	$(V_{CB} = 0 \text{ V, f} = 1.0 \text{ MHz})$	C _{obo}	-	30	_	pF
Turn-On Time	$(I_{BI} = -50 \text{ mA}, I_{C} = -500 \text{ mA}, R_{L} = 3.0 \Omega)$	t _{on}	-	50	-	ns
Turn–Off Time $(I_{B1} = I_{B2} = -50 \text{ mA}, I_{C} = -500 \text{ mA}, R_{L} = 3.0 \Omega)$			-	80	-	ns

Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%.
 Pulsed Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.



TYPICAL ELECTRICAL CHARACTERISTICS FOR Q1

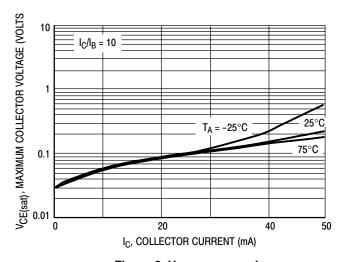


Figure 2. V_{CE(sat)} versus I_C

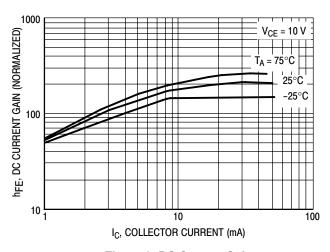


Figure 3. DC Current Gain

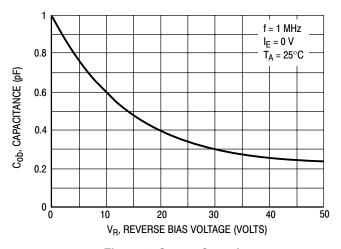


Figure 4. Output Capacitance

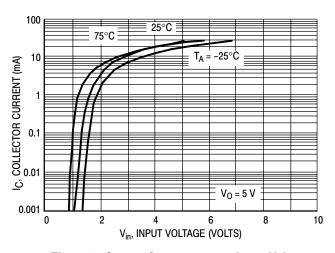


Figure 5. Output Current versus Input Voltage

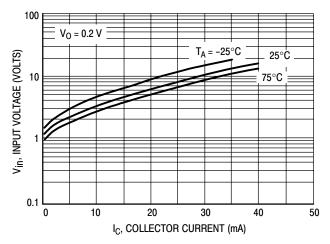


Figure 6. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS FOR Q2

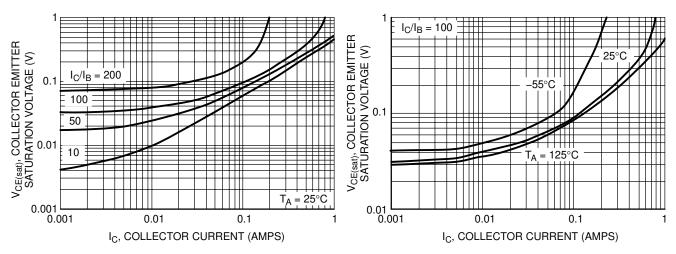


Figure 7. Collector Emitter Saturation Voltage vs. Collector Current

Figure 8. Collector Emitter Saturation Voltage vs. Collector Current

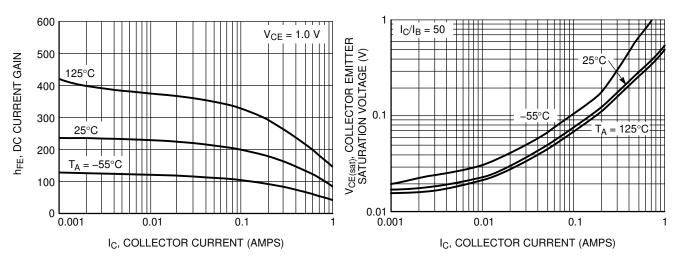


Figure 9. DC Current Gain

Figure 10. Collector Emitter Saturation Voltage vs. Collector Current

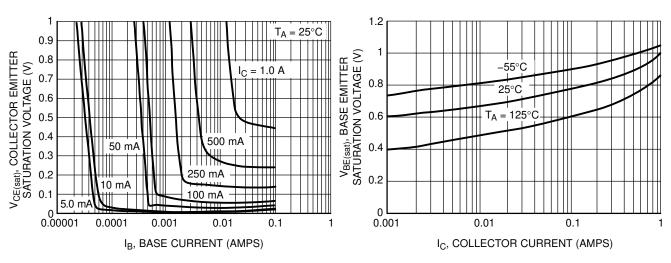
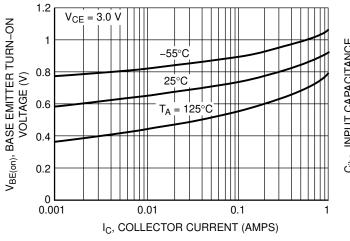


Figure 11. Collector Emitter Saturation Voltage vs Base Current

Figure 12. Base Emitter Saturation Voltage vs.
Collector Current



f = 1 MHz $I_C = 0 A$ $T_A = 25^{\circ}C$ C_{ibo}, INPUT CAPACITANCE $V_{\mathsf{EB}},$ EMITTER BASE VOLTAGE

Figure 13. Base Emitter Turn-On Voltage vs.
Collector Current

Figure 14. Input Capacitance

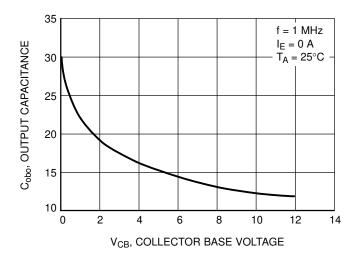
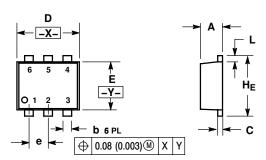


Figure 15. Output Capacitance

PACKAGE DIMENSIONS

SOT-563, 6 LEAD CASE 463A-01 ISSUE F

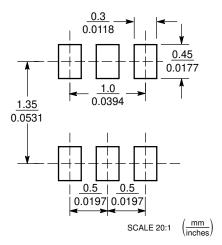


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
Е	1.10	1.20	1.30	0.043	0.047	0.051
е	0.5 BSC		0.02 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.50	1.60	1.70	0.059	0.062	0.066

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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